

Standard SCRs, 16A

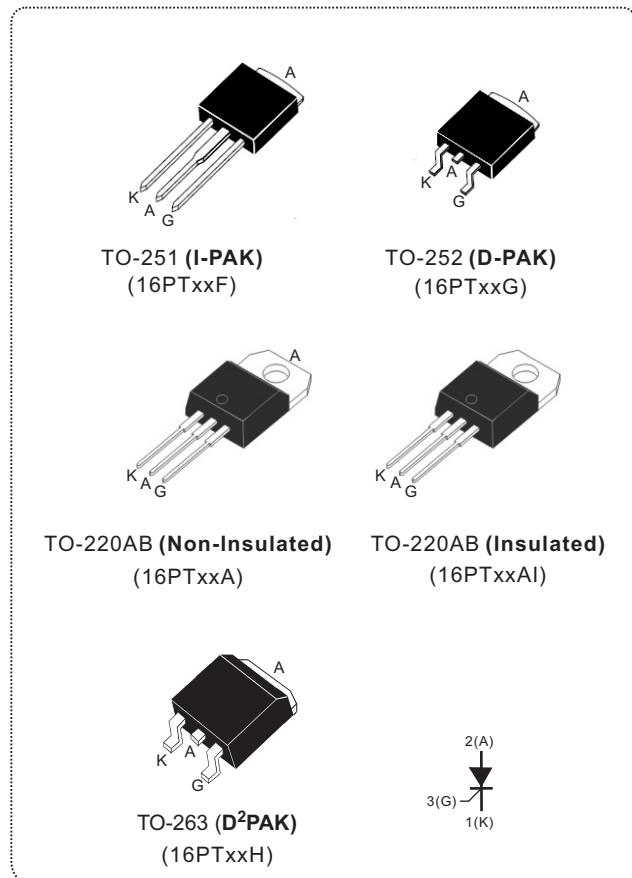
Main Features

Symbol	Value	Unit
$I_{T(RMS)}$	16	A
V_{DRM}/V_{RRM}	600 to 1000	V
I_{GT}	25	mA

DESCRIPTION

The 16PT series of silicon controlled rectifiers are high performance glass passivated technology, and are suitable for general purpose applications.

Using clip assembly technology, they provide a superior performance in surge current capabilities.



ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUE	UNIT
RMS on-state current full sine wave (180° conduction angle)	$I_{T(RMS)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	16	A
		TO-220AB insulated	$T_c=86^\circ C$		
Average on-state current (180° conduction angle)	$I_{T(AV)}$	TO-251/TO-252 TO-220AB/TO-263	$T_c=110^\circ C$	10	A
		TO-220AB insulated	$T_c=86^\circ C$		
Non repetitive surge peak on-state current (full cycle, T_j initial = 25°C)	I_{TSM}	$F=50$ Hz	$t = 20$ ms	190	A
		$F=60$ Hz	$t = 16.7$ ms	200	
I^2t Value for fusing	I^2t	$t_p = 10$ ms		180	A^2s
Critical rate of rise of on-state current $I_G = 2xI_{GT}$, $t_r \leq 100$ ns	dI/dt	$F = 60$ Hz	$T_j = 125^\circ C$	50	$A/\mu s$
Peak gate current	I_{GM}	$T_p = 20$ μs	$T_j = 125^\circ C$	4	A
Maximum gate power	P_{GM}	$T_p = 20\mu s$	$T_j = 125^\circ C$	10	W
Average gate power dissipation	$P_{G(AV)}$	$T_j = 125^\circ C$		1	W
Repetitive peak off-state voltage	V_{DRM}	$T_j = 125^\circ C$		600 to 1000	V
Repetitive peak reverse voltage	V_{RRM}				
Storage temperature range	T_{stg}			- 40 to + 150	$^\circ C$
Operating junction temperature range	T_j			- 40 to + 125	

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
SYMBOL	TEST CONDITIONS			16PTxxxx		Unit		
				D	-			
I _{GT}	V _D = 12V, R _L = 33Ω			Min.	4	2		
				Max.	10	25		
V _{GT}				Max.	1.3	1.3		
V _{GD}	V _D = V _{DRM} , R _L = 3.3KΩ R _{GK} = 220Ω	T _j = 125°C		Min.	0.2	0.2		
I _H	I _T = 500mA, Gate open			Max.	10	40		
I _L	I _G = 1.2×I _{GT}			Max.	20	60		
dV/dt	V _D = 67% V _{DRM} , Gate open		T _j = 125°C	Min.	100	500		
V _{TM}	I _T = 32A, t _P = 380μs		T _j = 25°C	Max.	1.6			
I _{DRM} I _{RRM}	V _D =V _{DRM} , V _R =V _{RRM}		T _j = 25°C	Max.	5			
	R _{GK} = 220Ω		T _j = 125°C	Max.	2			
V _{to}	Threshold Voltage		T _j = 125°C	Max.	0.77			
R _d	Dynamic Resistance		T _j = 125°C	Max.	23			

DYNAMIC CHARACTERISTICS						
SYMBOL	PARAMETER	TEST CONDITIONS		VALUE		UNIT
				Min.	Typ.	
t _{gt}	Gate-controlled turn-on time	I _{TM} = 40A, V _D = V _{DRM} (Max.), I _G = 0.1A, dI _G /dt = 5A/μs, T _J = 25°C		-	2.0	-
t _q	Commutated turn-off time	V _D = 67% V _{DRM} , I _{TM} = 30A, V _R = 25V, R _{GK} = 100Ω, dI _{TM} /dt = 30A/μs, dV _D /dt = 50V/μs, T _J = 125°C		-	70	-

THERMAL RESISTANCE							
SYMBOL	Parameter				VALUE	UNIT	
R _{th(j-c)}	Junction to case (DC)		IPAK/DPAK/TO-220AB/TO-263		1.1	°C/W	
R _{th(j-a)}	Junction to ambient	S = 1 cm ²	TO-263(D ² PAK)		45	°C/W	
		S = 0.5 cm ²	TO-252(D-PAK)		70		
		TO-220AB		60			
		TO-251(I-PAK)		100			

S=Copper surface under tab

PRODUCT SELECTOR						
PART NUMBER	VOLTAGE (xx)			SENSITIVITY	PACKAGE	
	600 V	800 V	1000 V			
16PTxxA/16PTxxAI	V	V	V	25 mA	TO-220AB	
16PTxxF	V	V	V	25 mA	I-PAK	
16PTxxG	V	V	V	25 mA	D-PAK	
16PTxxH	V	V	V	25 mA	D ² PAK	
16PTxxA-D/16PTxxAI-D	V	V	V	4-10 mA	TO-220AB	
16PTxxF-D	V	V	V	4-10 mA	I-PAK	
16PTxxG-D	V	V	V	4-10 mA	D-PAK	
16PTxxH-D	V	V	V	4-10 mA	D ² PAK	

ORDERING INFORMATION

ORDERING TYPE	MARKING	PACKAGE	WEIGHT	BASE Q'TY	DELIVERY MODE
16PTxxA/16PTxxA-D	16PTxxA/16PTxxA-D	TO-220AB	2.0g	50	Tube
16PTxxAI/16PTxxAI-D	16PTxxAI/16PTxxAI-D	TO-220AB (insulated)	2.3g	50	Tube
16PTxxF/16PTxxF-D	16PTxxF/16PTxxF-D	TO-251(I-PAK)	0.40g	80	Tube
16PTxxG/16PTxxG-D	16PTxxG/16PTxxG-D	TO-252(D-PAK)	0.38g	80	Tube
16PTxxH/16PTxxH-D	16PTxxH/16PTxxH-D	TO-263(D ² PAK)	2.0g	50	Tube

Note: xx = voltage

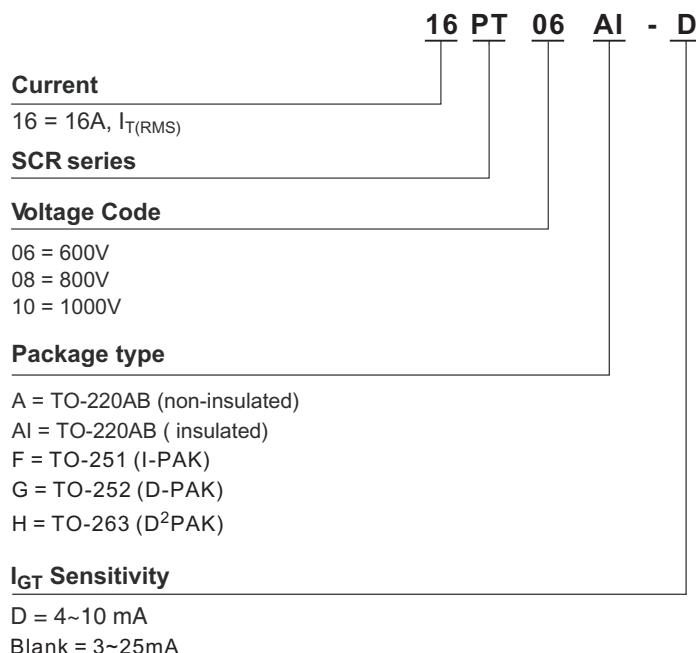
ORDERING INFORMATION SCHEME


Fig.1 Maximum average power dissipation versus average on-state current.

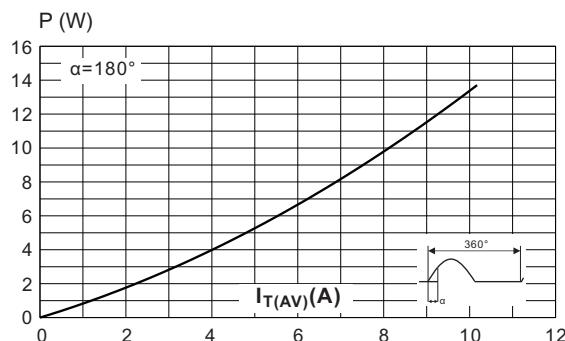
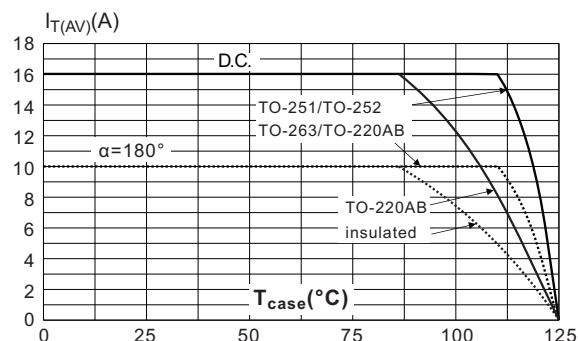


Fig.2 Average and D.C. on-state current versus case temperature.



**Fig.3 Average and D.C. on-state current versus ambient temperature.
(copper surface under tab: $S=1\text{cm}^2$)
(D²PAK)**

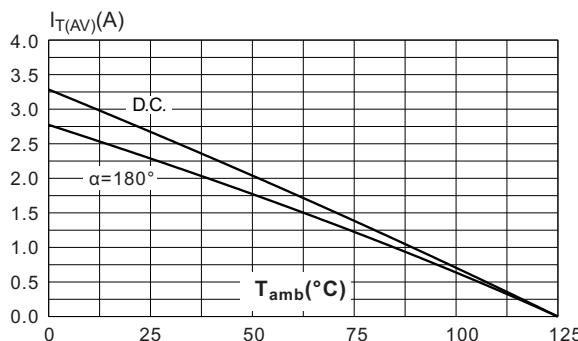


Fig.4 Relative variation of thermal impedance versus pulse duration.

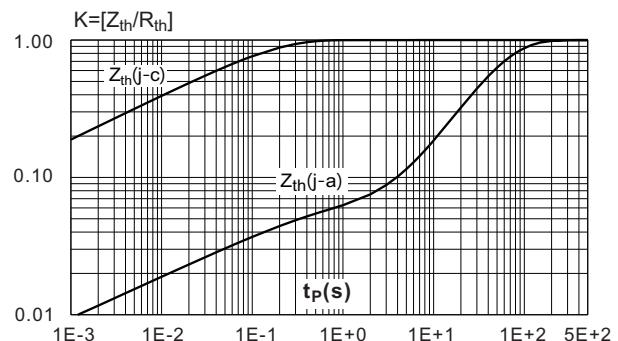


Fig.5 Relative variation of gate trigger current, holding current and latching current and latching current versus junction temperature.

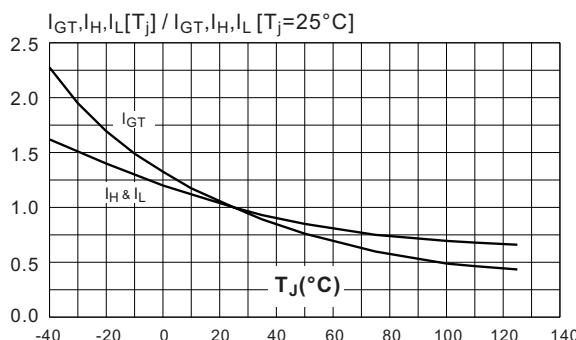


Fig.6 Surge peak on-state current versus number of cycles.

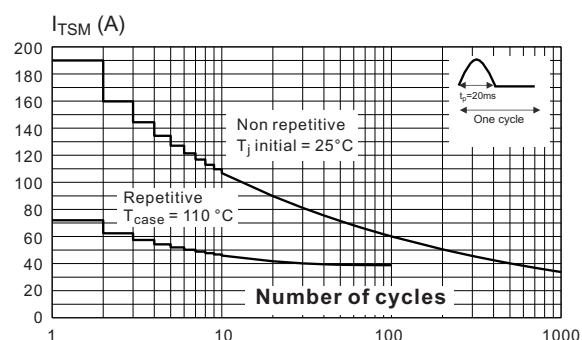


Fig.7 Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10\text{ ms}$, and corresponding values of I^2t

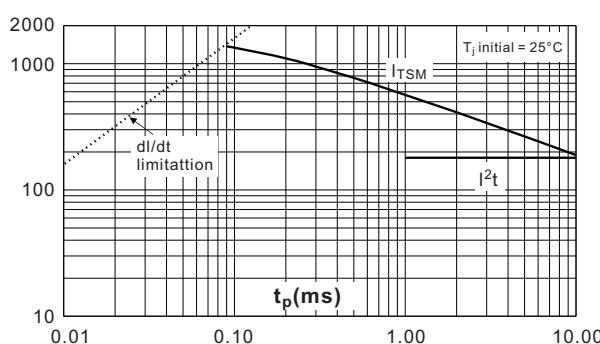


Fig.8 On-state characteristics (maximum values)

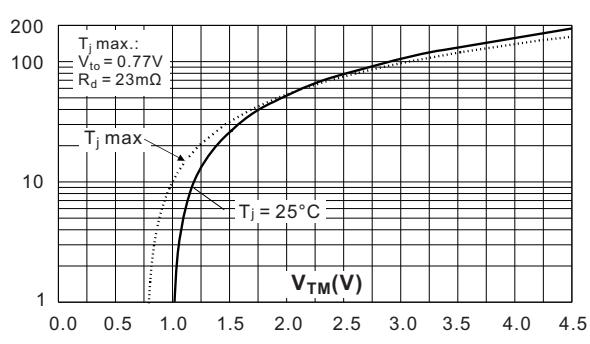
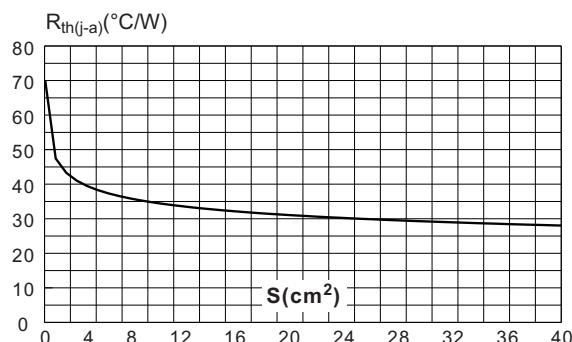
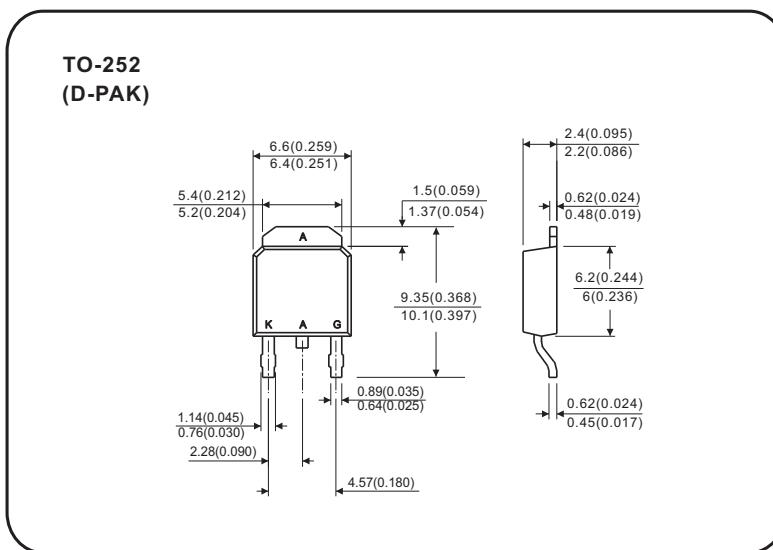
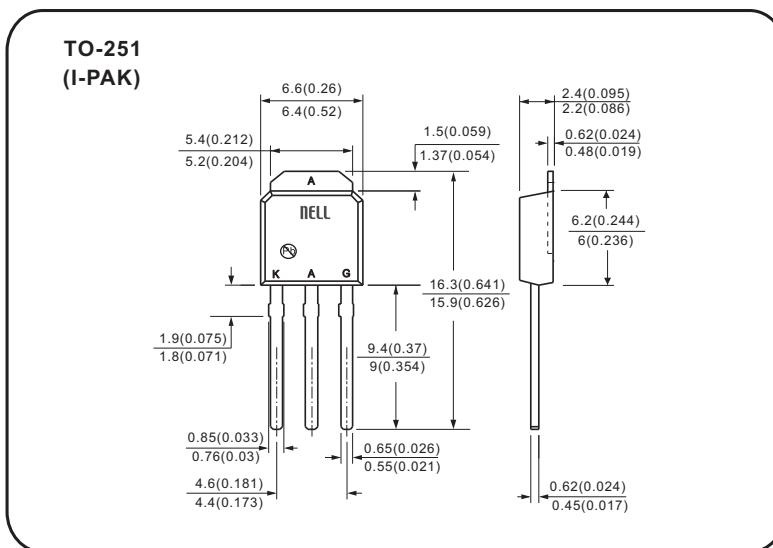


Fig.9 Thermal resistance junction to ambient versus copper surface under tab (epoxy printed circuit board Fr4, copper thickness:35 µm)(D²PAK)

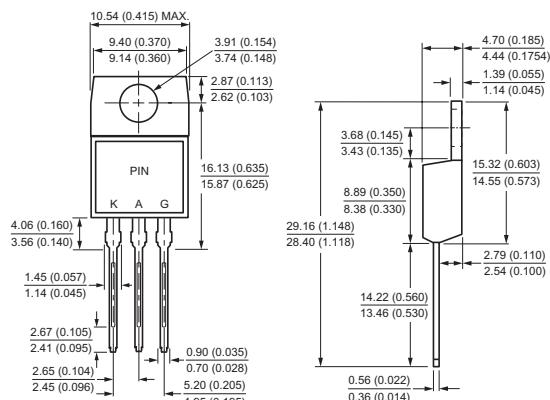
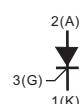
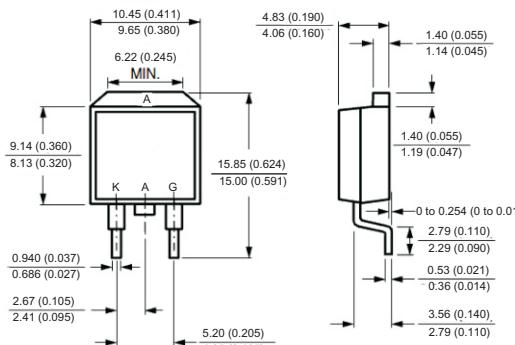


Case Style



All dimensions in millimeters(inches)

Case Style

TO-220AB

TO-263(D²PAK)


All dimensions in millimeters(inches)